

ABSTRACT

An interposer capable of preventing breaking of a wiring pattern with an IC chip loaded on a package substrate. Stress due to a difference in thermal expansion coefficient between a multilayer printed wiring board having a large thermal expansion and the IC chip having a small thermal expansion can be absorbed by locating the interposer between the package substrate and the IC chip. Particularly by using an insulation substrate whose Young's modulus is 55 to 440Gpa as the insulation substrate constituting the interposer, stress is absorbed within the interposer.